

Features

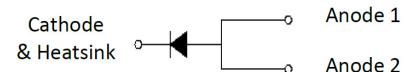
- Low profile - typical height 1.1 mm
- Low forward voltage drop
- Low leakage current
- Moisture sensitivity: level 1, per J-STD-020
- High temperature soldering guaranteed: 260°C/10 seconds
- Halogen-free according to IEC 61249-2-21 definition



Package:
 eSGC (TO-277)

Applications

For low voltage high frequency inverters, DC/DC converters and polarity protection applications.



Schematic Diagram

Maximum Ratings ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Maximum Repetitive Peak Reverse Voltage	V _{RRM}	60	V
Maximum RMS Voltage	V _{RMS}	42	V
Maximum DC Blocking Voltage	V _D	60	V
Maximum Average Forward Rectified Current	I _{F(AV)¹}	5.0	A
	I _{F(AV)²}	3.0	
Peak Forward Surge Current (8.3ms single half sine-wave superimposed on rated load)	I _{FSM}	175	A
Operating Junction and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Test Conditions		Symbol	Typ.	Max.	Unit	
Maximum Instantaneous Forward Voltage	I _F =1A	T _A =25°C	V _F	0.40	-	V	
	I _F =2A			0.44	-		
	I _F =5A			0.52	0.65		
	I _F =1A	T _A =75°C		0.35	-		
	I _F =2A			0.40	-		
	I _F =5A			0.50	-		
	I _F =1A	T _A =125°C		0.28	-		
	I _F =2A			0.35	-		
	I _F =5A			0.47	0.6		
Maximum DC Reverse Current at Rated DC Blocking Voltage	Rated V _R	T _A =25°C	I _R	0.04	0.2	mA	
		T _A =75°C		0.6	3		
		T _A =125°C		8.7	30		
Junction Capacitance	4.0 V, 1 MHz		C _J	220		pF	
Typical Thermal Resistance	Junction to Lead		R _{θJL}	15		°C/W	

Notes 1) Mounted on Aluminum Substrate PCB

2) Mounted on recommended copper pad area, free air.

Ratings and Characteristics Curves ($T_A = 25^\circ C$ unless otherwise noted)

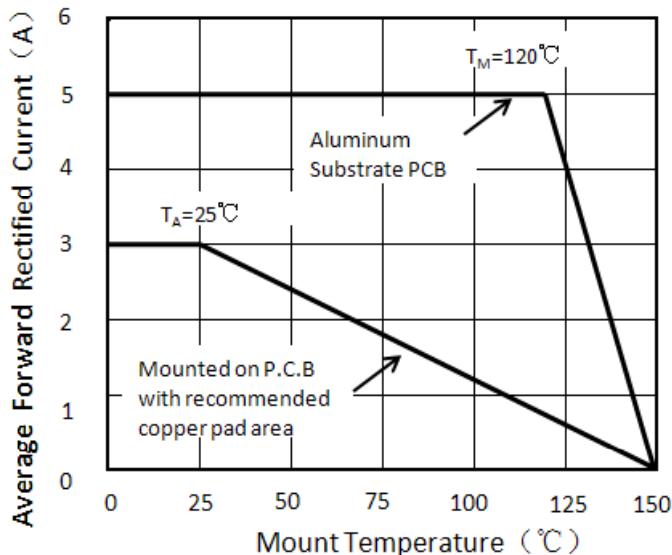


Figure 1. Forward Current Derating Curve

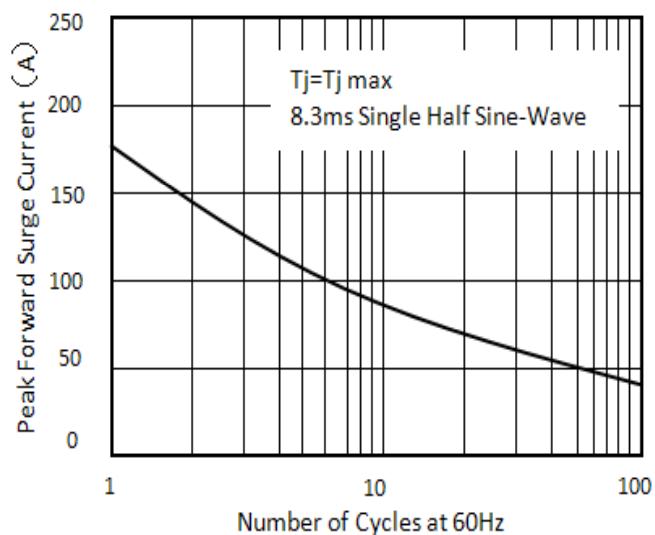


Figure 2. Maximum Non-Repetitive Peak Forward Surge Current

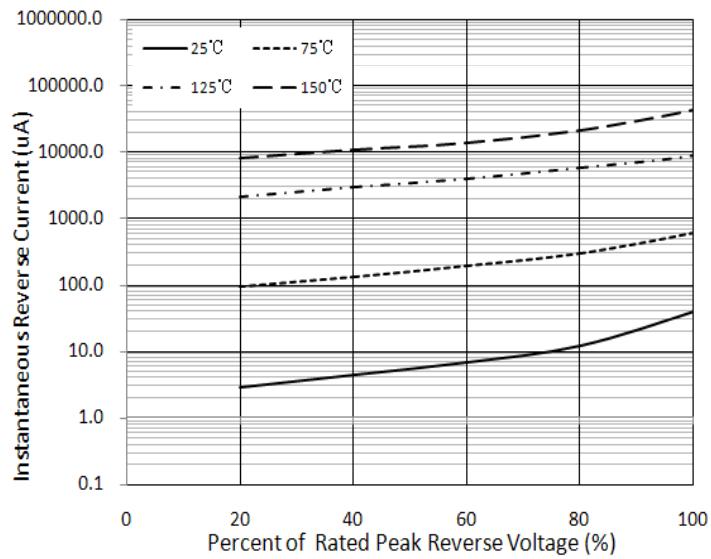


Figure 3. Typical Reverse Characteristics

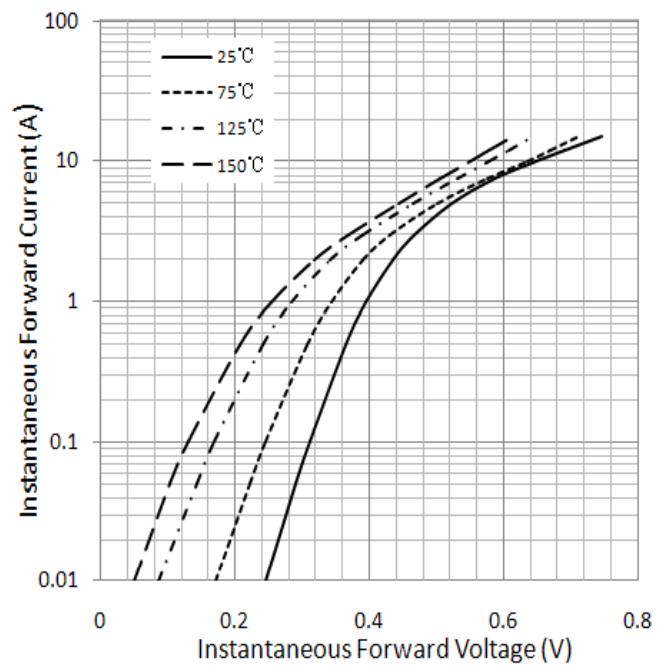
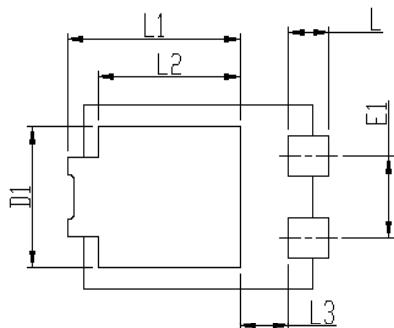
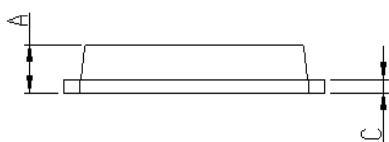
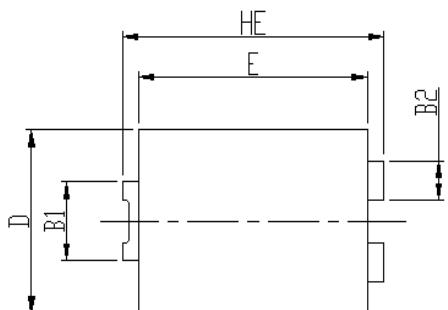


Figure 4. Typical Instantaneous Forward Characteristics

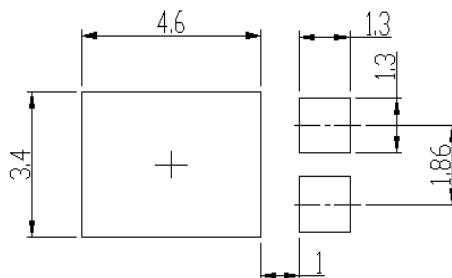
Package Outline Dimensions



eSGC (TO-277)

DIM	Unit: mm		Unit: inch	
	MIN	MAX	MIN	MAX
HE	6.4	6.6	0.252	0.260
E	5.6	5.8	0.220	0.228
D	4.1	4.3	0.161	0.169
B1	1.7	1.9	0.067	0.075
B2	0.8	1	0.031	0.039
A	1.05	1.2	0.041	0.047
C	0.3	0.4	0.012	0.016
L	0.85	1.1	0.033	0.043
L1	4.2	4.4	0.165	0.173
L2	3.52	Typ.	0.139	Typ.
L3	1.1	1.4	0.043	0.055
D1	3	3.3	0.118	0.130
E1	1.86	Typ.	0.073	Typ.

Soldering footprint



Packing Information

Packing quantities

5000 pcs/Reel, 12 mm Tape, 13" Reel

Tape & Reel Specification

